

High Performance ASIC Cooling Solutions w/Thermal Tape Attachment*

DIGI-KEY PART # **ATS1343-ND**

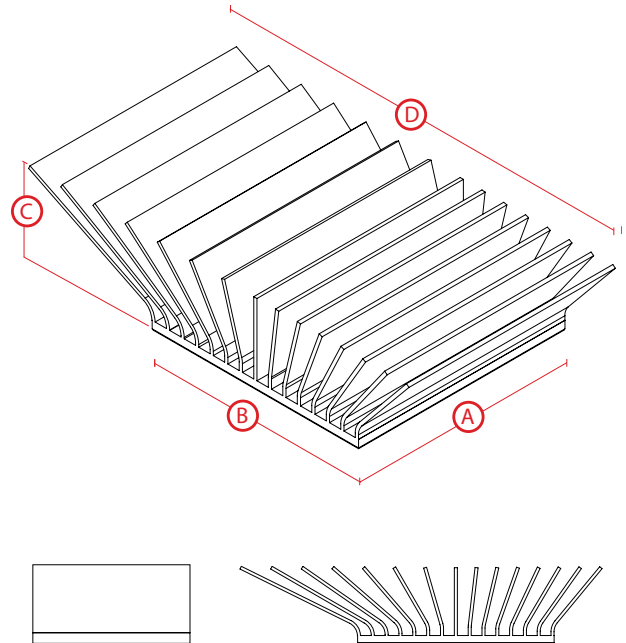
ATS PART # ATS-56012-C3-R0

Features & Benefits

maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

Designed specifically for ASIC package and their unique cooling requirements

Comes preassembled with high performance thermal interface material



Thermal Performance Table

| AIR VELOCITY | | THERMAL RESISTANCE | |
|--------------|-----|--------------------|---------------|
| FT/MIN | M/S | °C/W (UNDUCTED) | °C/W (DUCTED) |
| 200 | 1.0 | 2.8 | 1.4 |
| 300 | 1.5 | 2.1 | |
| 400 | 2.0 | 1.77 | |
| 500 | 2.5 | 1.57 | |
| 600 | 3.0 | 1.43 | |
| 700 | 3.5 | 1.33 | |
| 800 | 4.0 | 1.25 | |

Product Details†

| DIMENSION A | DIMENSION B | DIMENSION C§ | DIMENSION D | TIM‡ | FINISH |
|-------------|-------------|--------------|-------------|------|---------------|
| 42 | 42 | 16 | 62 | C675 | GOLD-ANODIZED |

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or www.qats.com

* RoHS Compliant

‡ TIM = Thermal Interface Material

† Dimensions are measured in millimeters

§ Dimension C = the height of the heat sink shown above and does not include the height of the attachment method



ATS ADVANCED THERMAL SOLUTIONS, INC.

Innovations in Thermal Management®



To place an order, please visit www.digikey.com